LISTING OF THE CLAIMS

The following Listing of the Claims replaces all prior listings of the claims within this application.

No claims are amended herein.

Claims 13-18 are newly added herein.

1. (original) A method for operating a multi-chamber fabrication tool comprising:

providing a multi-chamber fabrication tool comprising a series of chambers;

defining for each chamber within the series of chambers a minimum of one fabrication process to provide a series of fabrication processes corresponding with the series of chambers, wherein at least one fabrication process may be undertaken within more than one chamber and at least one chamber has defined therein more than one fabrication process including the at least one fabrication process which may be undertaken within more than one chamber;

processing within the multi-chamber fabrication tool a substrate while employing the at least one fabrication process which may be undertaken within more than one chamber, wherein a chamber within which is processed the substrate while employing the at least one fabrication process which may be undertaken within more than one chamber is selected such as to optimize utilization of the multi-chamber fabrication tool.

2. (original) The method of claim 1 wherein the substrate is employed within a microelectronic fabrication selected from the group consisting of integrated circuit microelectronic fabrications, ceramic substrate microelectronic fabrications, solar cell optoelectronic microelectronic fabrications, sensor image array optoelectronic microelectronic fabrications and display image array optoelectronic microelectronic fabrications.

3. (previously presented) The method of claim 1 wherein the series of chambers comprises at least about four chambers.

4. (original) The method of claim 1 wherein the series of fabrication processes is selected from the group consisting of vacuum etch processes, vacuum deposition processes and vacuum implantation processes

5. (original) The method of claim 1 further comprising:

defining a series of chamber constraints for the series of chambers;

defining a series of process constraints for the series of processes; and

defining a series of substrate constraints for the substrate.

6. (original) The method of claim 5 wherein the series of chamber constraints, the series of process constraints and the series of substrate constraints is prioritized through use of an algorithm when selecting the chamber within which is processed the substrate.

7. – 12. (canceled)

13. (new) A method for operating a multi-chamber fabrication tool comprising:

providing a multi-chamber fabrication tool comprising a series of chambers;

defining for each chamber within the series of chambers a minimum of one fabrication process to provide a series of fabrication processes corresponding with the series of chambers, wherein at least one fabrication process may be undertaken within more than one chamber;

processing within the multi-chamber fabrication tool a substrate while employing the at least one fabrication process which may be undertaken within more than one chamber, wherein a chamber within which is processed the substrate while employing the at least one fabrication process which may be undertaken within more than one chamber is selected such as to optimize utilization of the multi-chamber fabrication tool.

14. (new) The method of claim 1 wherein the substrate is employed within a microelectronic fabrication selected from the group consisting of integrated circuit microelectronic fabrications, ceramic substrate microelectronic fabrications, solar cell optoelectronic microelectronic fabrications, sensor image array optoelectronic microelectronic fabrications and display image array optoelectronic microelectronic fabrications.

15. (new) The method of claim 1 wherein the series of chambers comprises at least about four chambers.

16. (new) The method of claim 1 wherein the series of fabrication processes is selected from the group consisting of vacuum etch processes, vacuum deposition processes and vacuum implantation processes

17. (new) The method of claim 1 further comprising:

defining a series of chamber constraints for the series of chambers;

defining a series of process constraints for the series of processes; and

defining a series of substrate constraints for the substrate.

18. (new) The method of claim 5 wherein the series of chamber constraints, the series of process constraints and the series of substrate constraints is prioritized through use of an algorithm when selecting the chamber within which is processed the substrate.